

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number					
		PMEG2010EPK-Q					
		Part Description					
		Nexperia DHAM					
		MCD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
	TEST						
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113					
		Bake Tamb = 125 °C	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	208	9760	0	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet					
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0	
	TC	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	53	2400	0	
	UHAST	JESD22-A118					
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	- 96 hours	53	2400	0	
# AJ UI	Olibiased HAST	· · · · · · · · · · · · · · · · · · ·					
		JESD22-A102					
" A O II	AC Autoclave	Tamb = 121 °C, RH = 100 %					
# A3 alt	Autociave	Pressure = 205 kPa (29.7 psia)					
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of					
# A2 alt		rated reverse voltage ^{[1], [2]}	1000 hours	53	2400	0	
# AZ ait	. cperature Reverse Blas	MIL-STD-750 Method 1037	1000 110015	J.5	2400	U	
	IOL	ton = toff, devices powered to insure ΔT_i =					
# A5	Intermittent Operating Life		1000 hours	49	2560	0	
+ U3	Intermittent Operating Life	100 C 101 13000 Cycles	1000 110015	77	2300	U	
	RSH	JESD22-A111					
# C8	Resistance to Solder Heat		10 s	n.a.	n.a.	n.a.	
,	SD	200 0 - 0 0	10 3	mu.	mu.	11.0.	
# C10	Solderability	J-STD-002		37	1110	0	
, 010	20.acrubincy	, o.b ooc		J1	1110	v	

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.